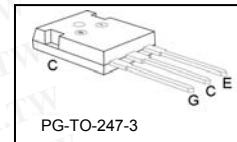
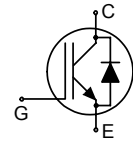


## Fast IGBT in NPT-technology with soft, fast recovery anti-parallel EmCon diode

- 75% lower  $E_{off}$  compared to previous generation combined with low conduction losses
- Short circuit withstand time – 10  $\mu$ s
- Designed for:
  - Motor controls
  - Inverter
- NPT-Technology for 600V applications offers:
  - very tight parameter distribution
  - high ruggedness, temperature stable behaviour
  - parallel switching capability
- Very soft, fast recovery anti-parallel EmCon diode
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC<sup>1</sup> for target applications
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	$V_{CE}$	$I_C$	$V_{CE(sat)}$	$T_j$	Marking	Package
SKW30N60	600V	30A	2.5V	150°C	K30N60	PG-TO-247-3

### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	600	V
DC collector current	$I_C$	41	A
$T_C = 25^\circ\text{C}$		30	
$T_C = 100^\circ\text{C}$			
Pulsed collector current, $t_p$ limited by $T_{jmax}$	$I_{Cpuls}$	112	
Turn off safe operating area	-	112	
$V_{CE} \leq 600\text{V}, T_j \leq 150^\circ\text{C}$			
Diode forward current	$I_F$	41	
$T_C = 25^\circ\text{C}$		30	
$T_C = 100^\circ\text{C}$			
Diode pulsed current, $t_p$ limited by $T_{jmax}$	$I_{Fpuls}$	112	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time <sup>2</sup>	$t_{SC}$	10	$\mu$ s
$V_{GE} = 15\text{V}, V_{CC} \leq 600\text{V}, T_j \leq 150^\circ\text{C}$			
Power dissipation	$P_{tot}$	250	W
$T_C = 25^\circ\text{C}$			
Soldering temperature	$T_s$	260	$^\circ\text{C}$
wavesoldering, 1.6 mm (0.063 in.) from case for 10s			
Operating junction and storage temperature	$T_j, T_{stg}$	-55...+150	$^\circ\text{C}$

<sup>1</sup> J-STD-020 and JESD-022

<sup>2</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

### Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		0.5	K/W
Diode thermal resistance, junction – case	$R_{thJCD}$		1	
Thermal resistance, junction – ambient	$R_{thJA}$		40	

### Electrical Characteristic, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=500\mu A$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=30A$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1.7 -	2.1 2.5	2.4 3.0	
Diode forward voltage	$V_F$	$V_{GE}=0V, I_F=30A$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1.2 -	1.4 1.25	1.8 1.65	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=700\mu A, V_{CE}=V_{GE}$	3	4	5	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V, V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	- -	- -	40 3000	$\mu A$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=30A$	-	20	-	S
<b>Dynamic Characteristic</b>						
Input capacitance	$C_{iss}$	$V_{CE}=25V,$	-	1600	1920	pF
Output capacitance	$C_{oss}$	$V_{GE}=0V,$	-	150	180	
Reverse transfer capacitance	$C_{riss}$	$f=1\text{MHz}$	-	92	110	
Gate charge	$Q_{Gate}$	$V_{CC}=480V, I_C=30A$ $V_{GE}=15V$	-	140	182	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	13	-	nH
Short circuit collector current <sup>1)</sup>	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 10\mu s$ $V_{CC}\leq 600V,$ $T_j\leq 150^\circ\text{C}$	-	300	-	A

<sup>1)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

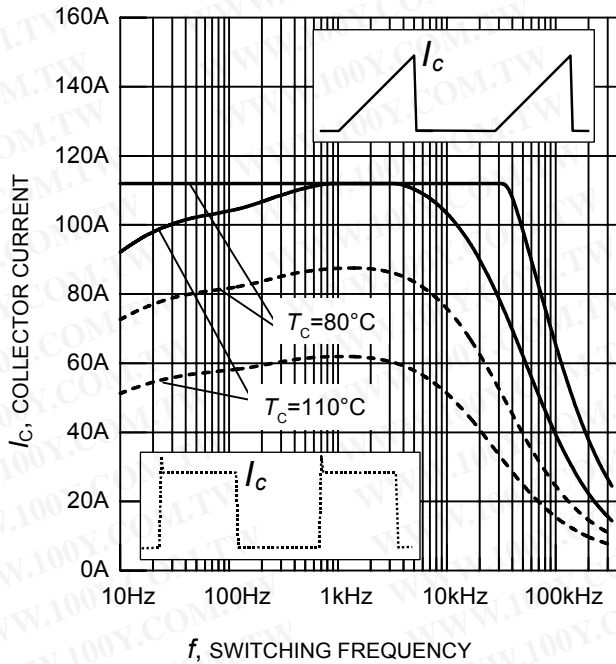
### Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=30\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=11\Omega$ , $L_{\sigma}^{1)}=180\text{nH}$ , $C_{\sigma}^{1)}=900\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	44	53	ns
Rise time	$t_r$		-	34	40	
Turn-off delay time	$t_{d(off)}$		-	291	349	
Fall time	$t_f$		-	58	70	
Turn-on energy	$E_{on}$		-	0.64	0.77	mJ
Turn-off energy	$E_{off}$		-	0.65	0.85	
Total switching energy	$E_{ts}$		-	1.29	1.62	
<b>Anti-Parallel Diode Characteristic</b>						
Diode reverse recovery time	$t_{rr}$	$T_j=25^\circ\text{C}$ , $V_R=200\text{V}$ , $I_F=30\text{A}$ , $di_F/dt=200\text{A}/\mu\text{s}$	-	400	-	ns
	$t_s$		-	32	-	
	$t_F$		-	368	-	
Diode reverse recovery charge	$Q_{rr}$		-	610	-	nC
Diode peak reverse recovery current	$I_{rrm}$		-	5.5	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	180	-	$\text{A}/\mu\text{s}$

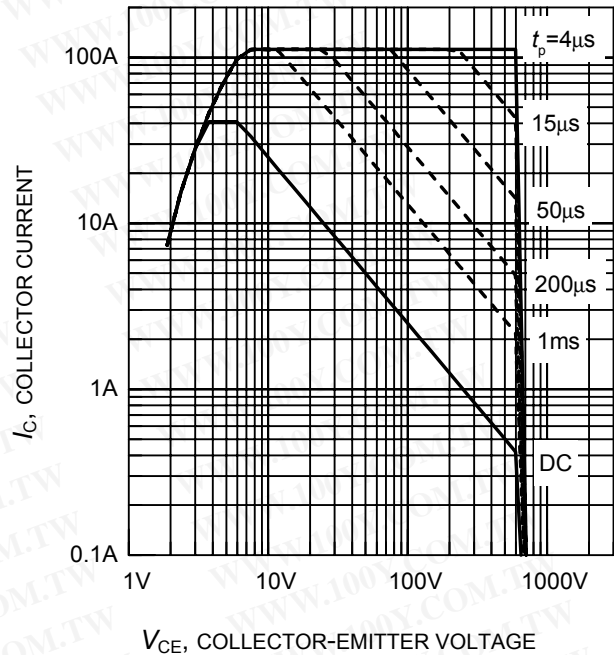
### Switching Characteristic, Inductive Load, at $T_j=150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=150^\circ\text{C}$ $V_{CC}=400\text{V}$ , $I_C=30\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=11\Omega$ , $L_{\sigma}^{1)}=180\text{nH}$ , $C_{\sigma}^{1)}=900\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	44	53	ns
Rise time	$t_r$		-	34	40	
Turn-off delay time	$t_{d(off)}$		-	324	389	
Fall time	$t_f$		-	67	80	
Turn-on energy	$E_{on}$		-	0.98	1.18	mJ
Turn-off energy	$E_{off}$		-	0.92	1.19	
Total switching energy	$E_{ts}$		-	1.90	2.38	
<b>Anti-Parallel Diode Characteristic</b>						
Diode reverse recovery time	$t_{rr}$	$T_j=150^\circ\text{C}$ $V_R=200\text{V}$ , $I_F=30\text{A}$ , $di_F/dt=200\text{A}/\mu\text{s}$	-	520	-	ns
	$t_s$		-	56	-	
	$t_F$		-	464	-	
Diode reverse recovery charge	$Q_{rr}$		-	1740	-	nC
Diode peak reverse recovery current	$I_{rrm}$		-	9.0	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	200	-	$\text{A}/\mu\text{s}$

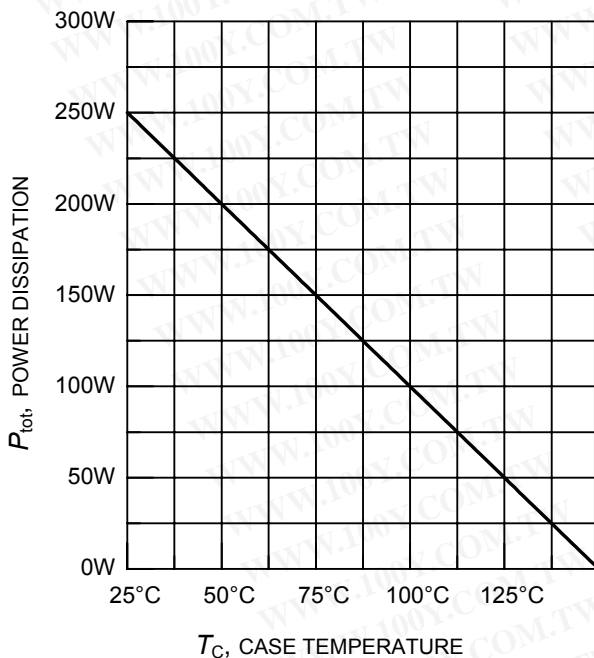
<sup>1)</sup> Leakage inductance  $L_{\sigma}$  and Stray capacity  $C_{\sigma}$  due to dynamic test circuit in Figure E.



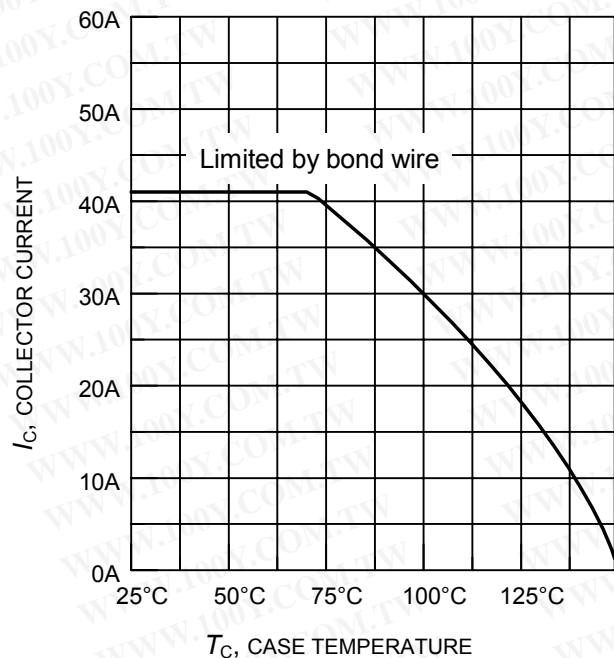
**Figure 1. Collector current as a function of switching frequency**  
 $(T_j \leq 150^\circ\text{C}, D = 0.5, V_{CE} = 400\text{V}, V_{GE} = 0/+15\text{V}, R_G = 11\Omega)$



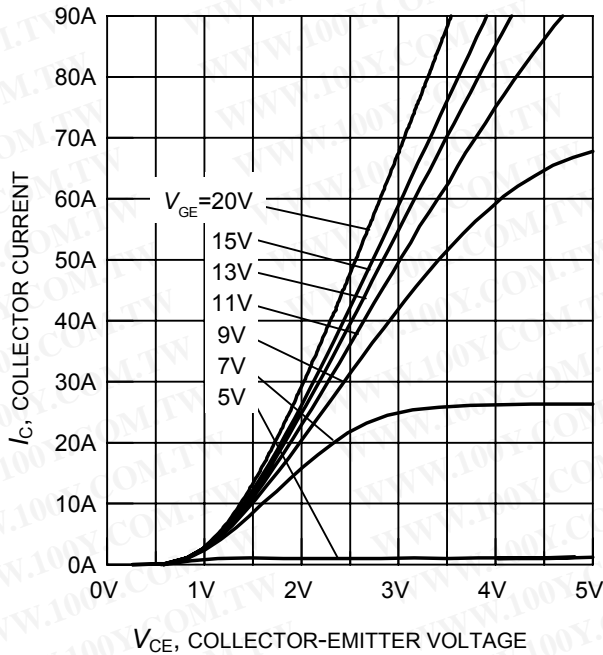
**Figure 2. Safe operating area**  
 $(D = 0, T_c = 25^\circ\text{C}, T_j \leq 150^\circ\text{C})$



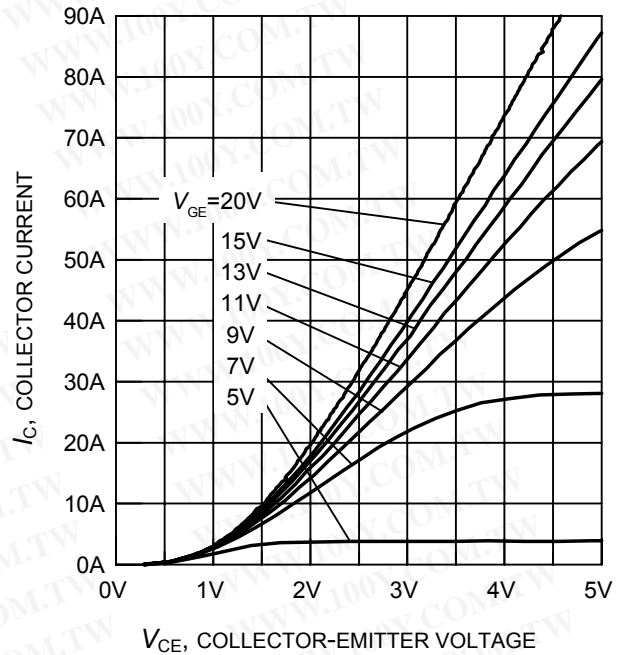
**Figure 3. Power dissipation as a function of case temperature**  
 $(T_j \leq 150^\circ\text{C})$



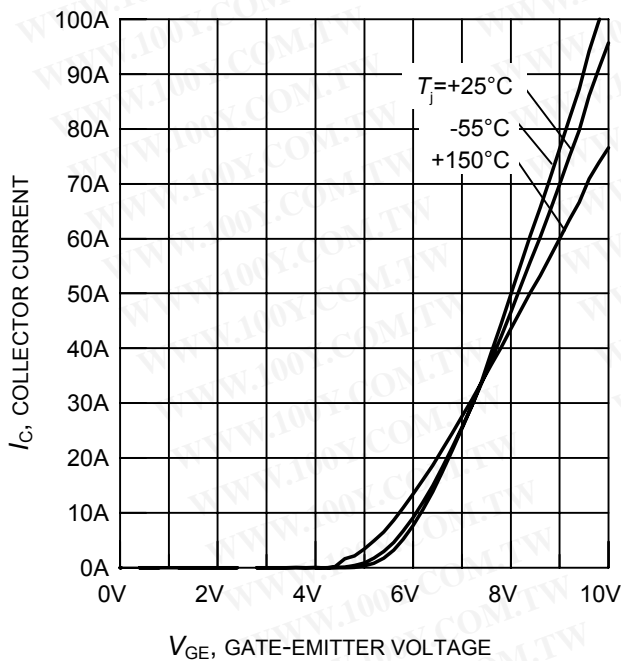
**Figure 4. Collector current as a function of case temperature**  
 $(V_{GE} \leq 15\text{V}, T_j \leq 150^\circ\text{C})$



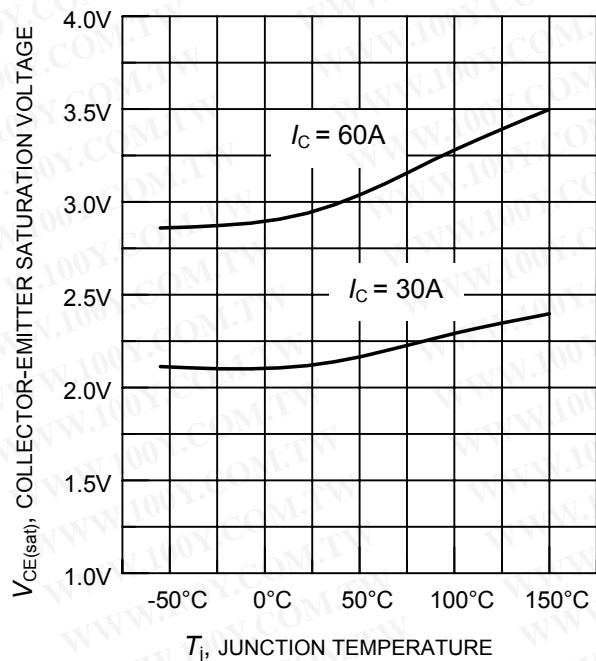
**Figure 5. Typical output characteristics**  
( $T_j = 25^\circ\text{C}$ )



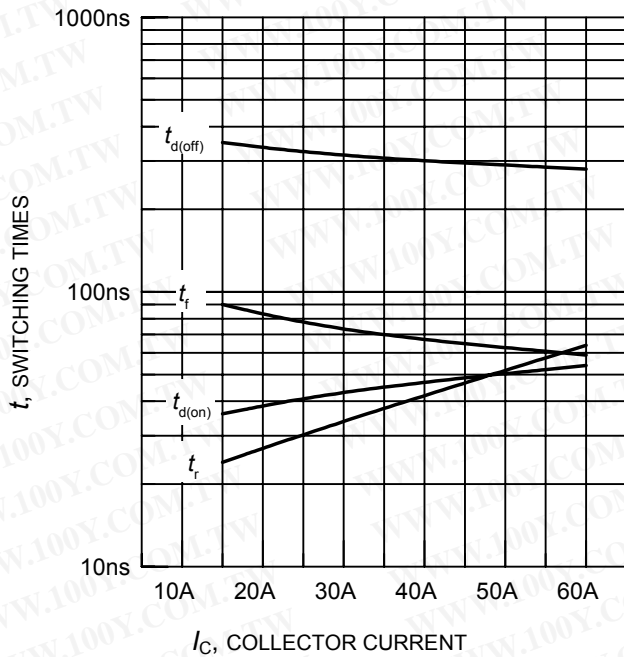
**Figure 6. Typical output characteristics**  
( $T_j = 150^\circ\text{C}$ )



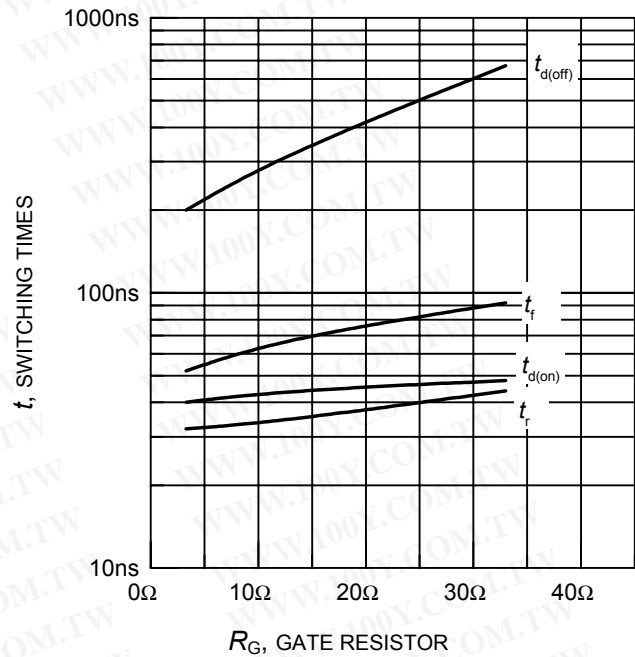
**Figure 7. Typical transfer characteristics**  
( $V_{CE} = 10\text{V}$ )



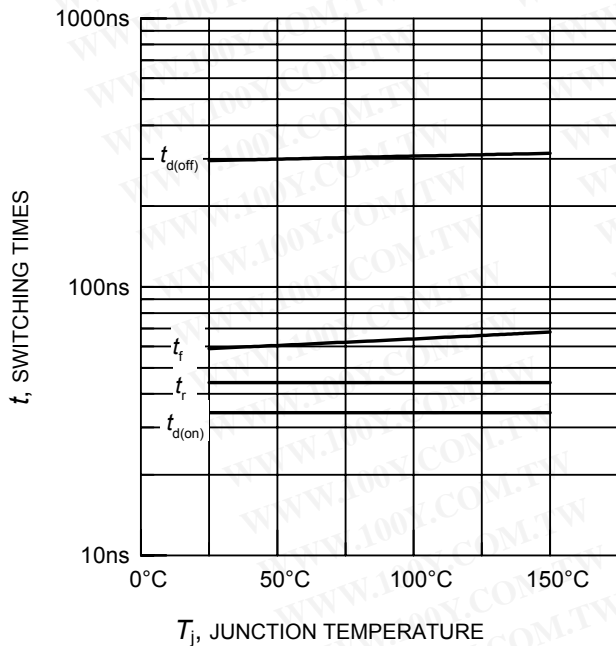
**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



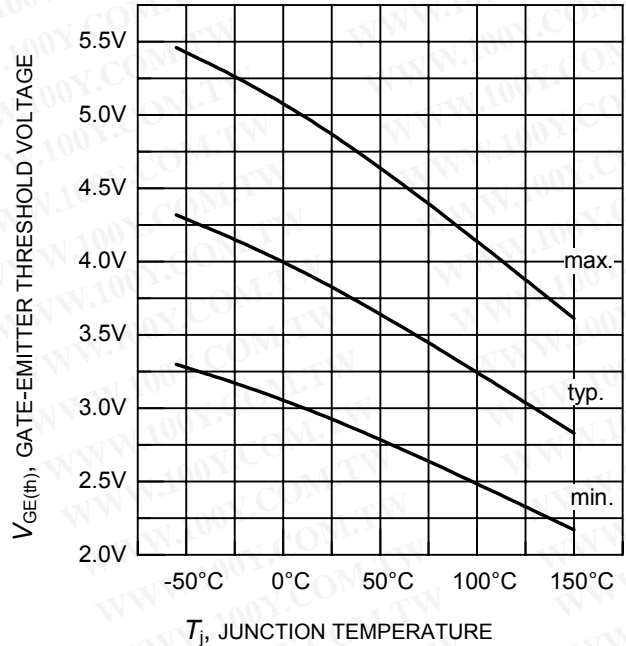
**Figure 9. Typical switching times as a function of collector current**  
 (inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/+15\text{V}$ ,  $R_G = 11\Omega$ ,  
 Dynamic test circuit in Figure E)



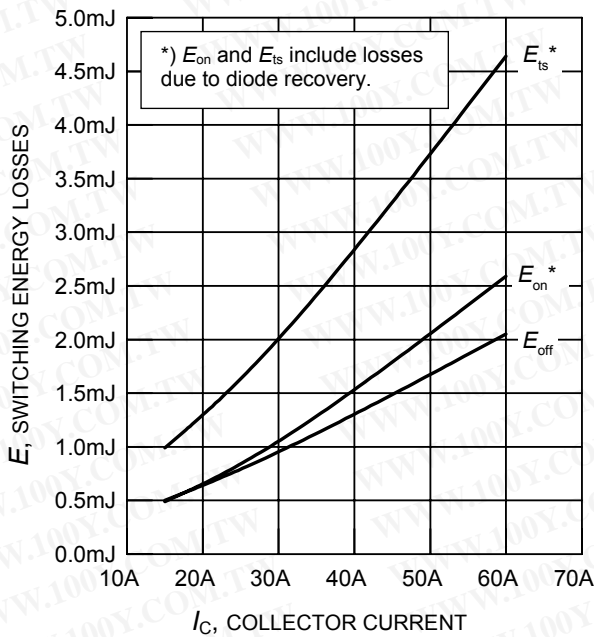
**Figure 10. Typical switching times as a function of gate resistor**  
 (inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/+15\text{V}$ ,  $I_C = 30\text{A}$ ,  
 Dynamic test circuit in Figure E)



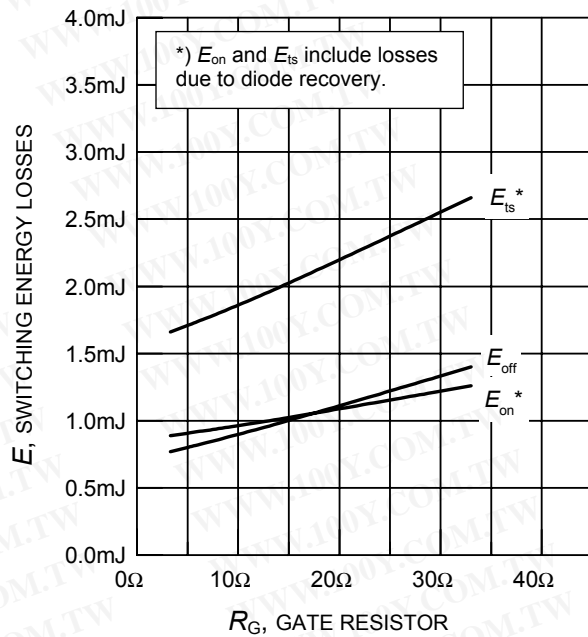
**Figure 11. Typical switching times as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  
 $I_C = 30\text{A}$ ,  $R_G = 11\Omega$ ,  
 Dynamic test circuit in Figure E)



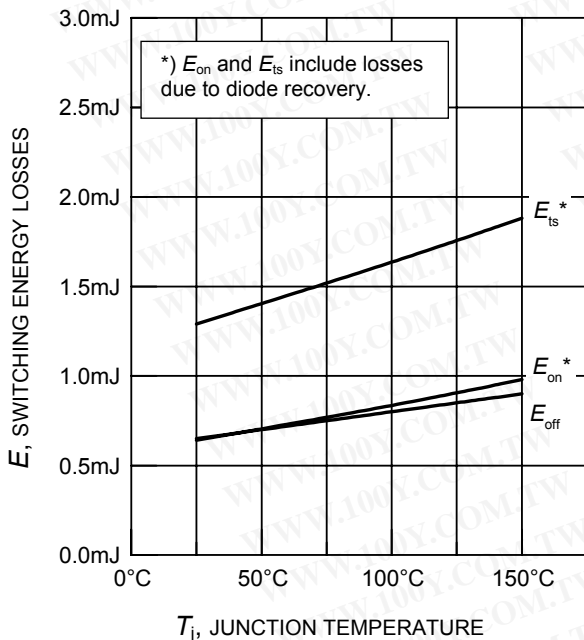
**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**  
 ( $I_C = 0.7\text{mA}$ )



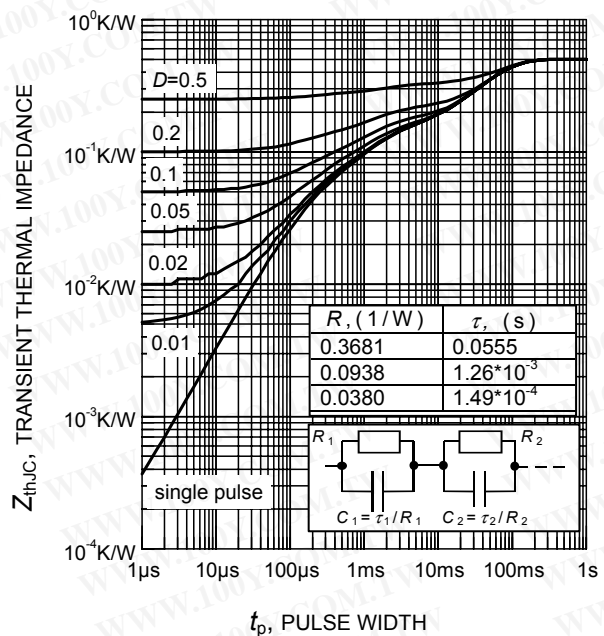
**Figure 13. Typical switching energy losses as a function of collector current**  
 (inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $R_G = 11\Omega$ , Dynamic test circuit in Figure E)



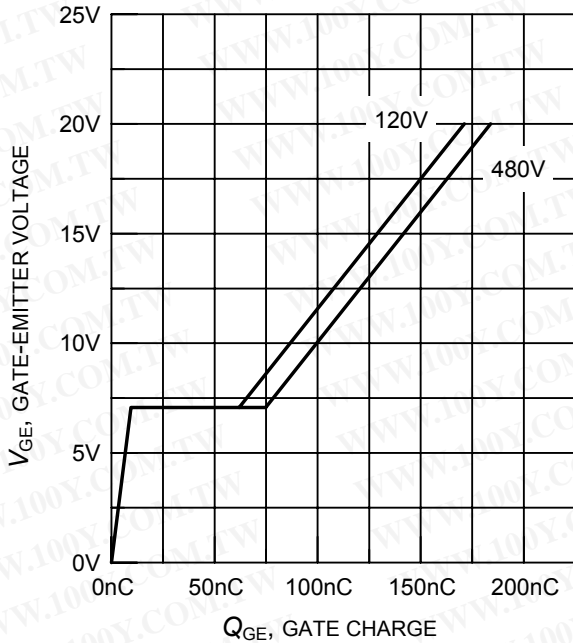
**Figure 14. Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $I_C = 30\text{A}$ , Dynamic test circuit in Figure E)



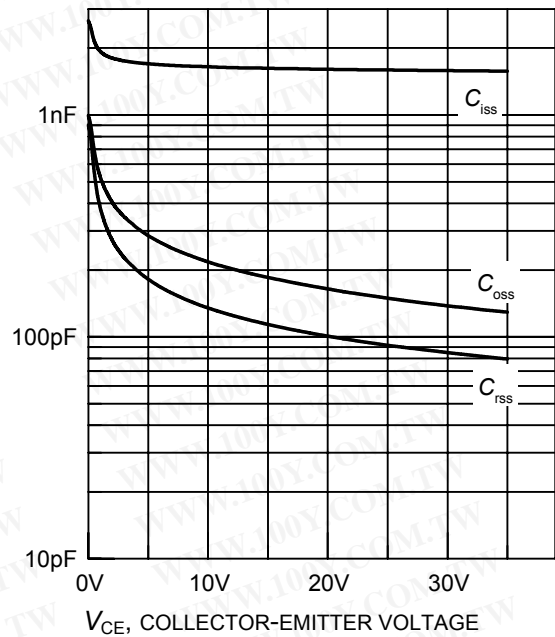
**Figure 15. Typical switching energy losses as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $I_C = 30\text{A}$ ,  $R_G = 11\Omega$ , Dynamic test circuit in Figure E)



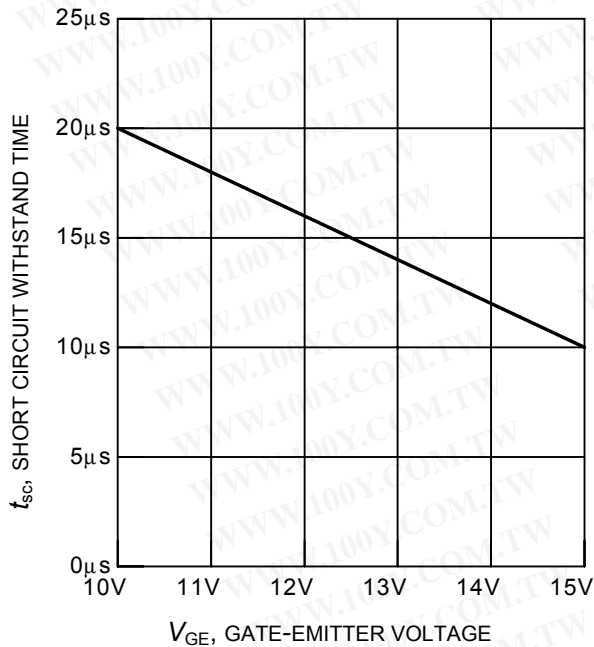
**Figure 16. IGBT transient thermal impedance as a function of pulse width**  
 ( $D = t_p / T$ )



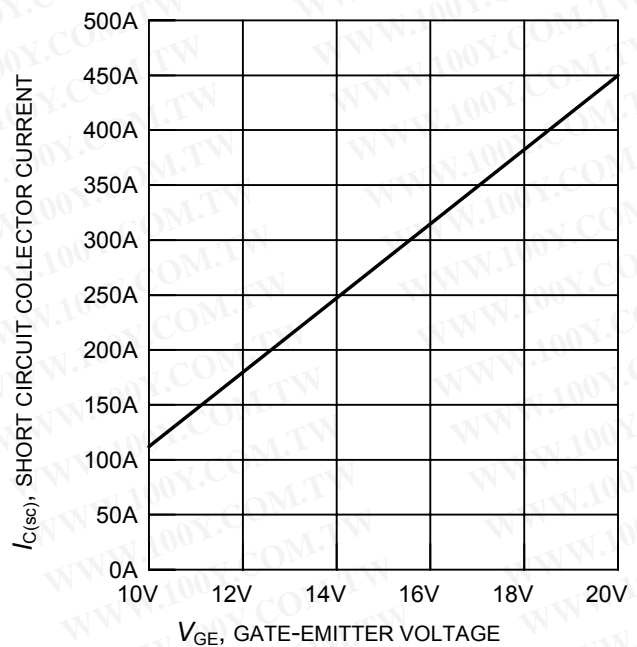
**Figure 17. Typical gate charge**  
( $I_C = 30A$ )



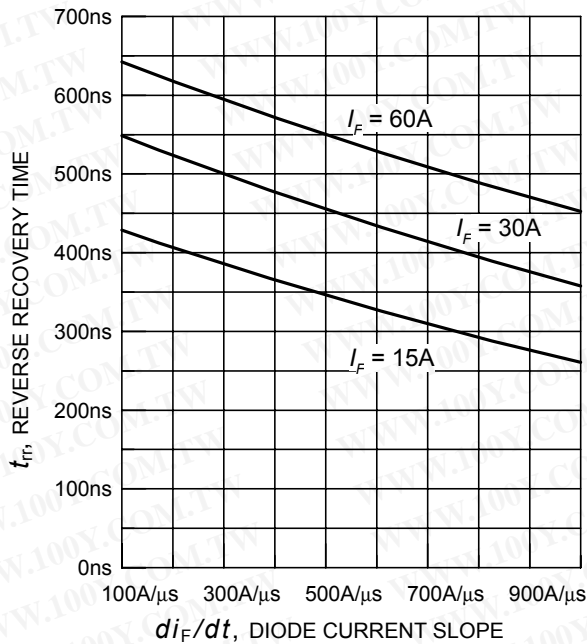
**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE} = 0V, f = 1MHz$ )



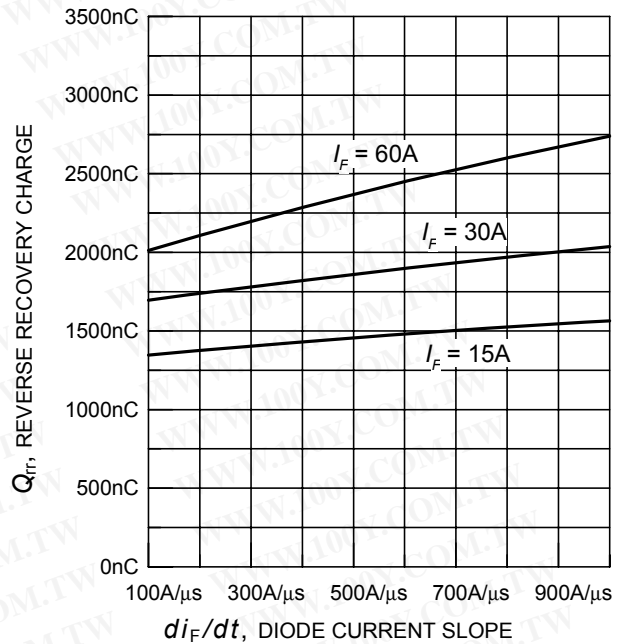
**Figure 19. Short circuit withstand time as a function of gate-emitter voltage**  
( $V_{CE} = 600V$ , start at  $T_j = 25^\circ C$ )



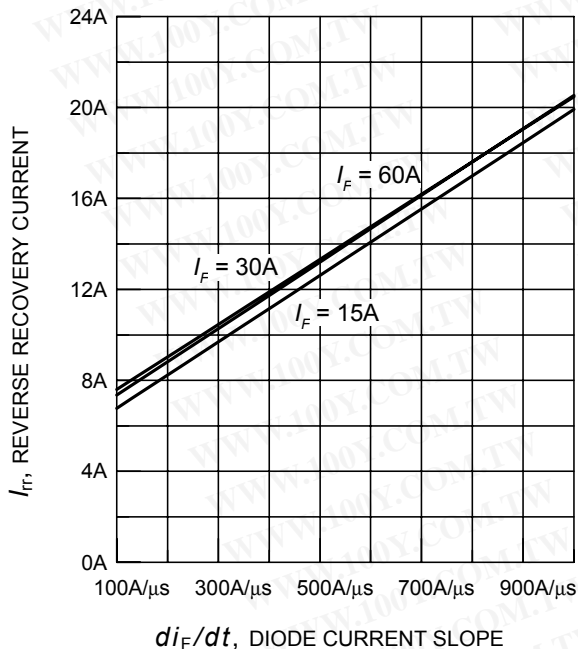
**Figure 20. Typical short circuit collector current as a function of gate-emitter voltage**  
( $V_{CE} \leq 600V, T_j = 150^\circ C$ )



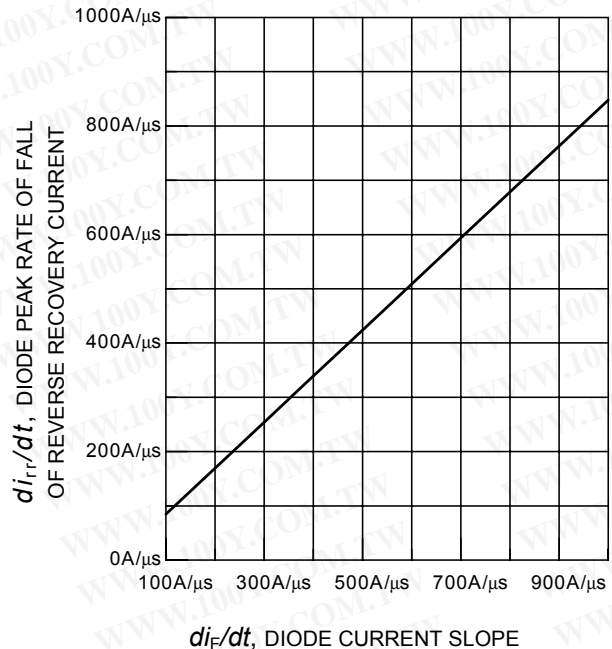
**Figure 21. Typical reverse recovery time as a function of diode current slope**  
 $(V_R = 200V, T_j = 125^\circ C,$   
 Dynamic test circuit in Figure E)



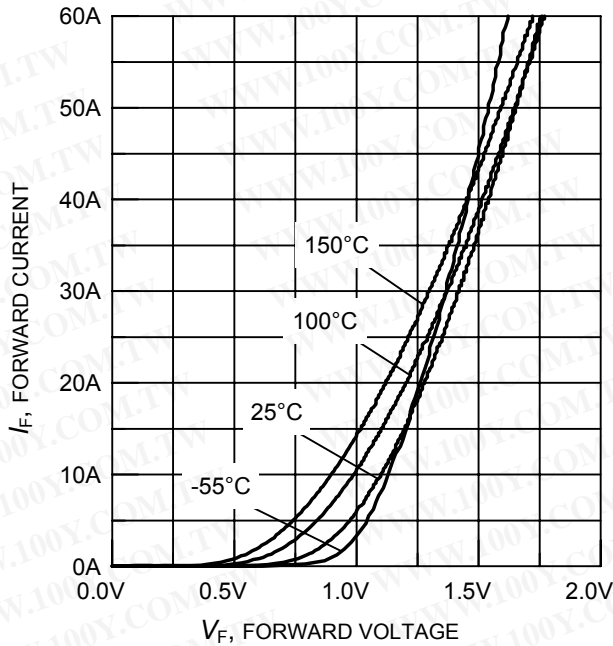
**Figure 22. Typical reverse recovery charge as a function of diode current slope**  
 $(V_R = 200V, T_j = 125^\circ C,$   
 Dynamic test circuit in Figure E)



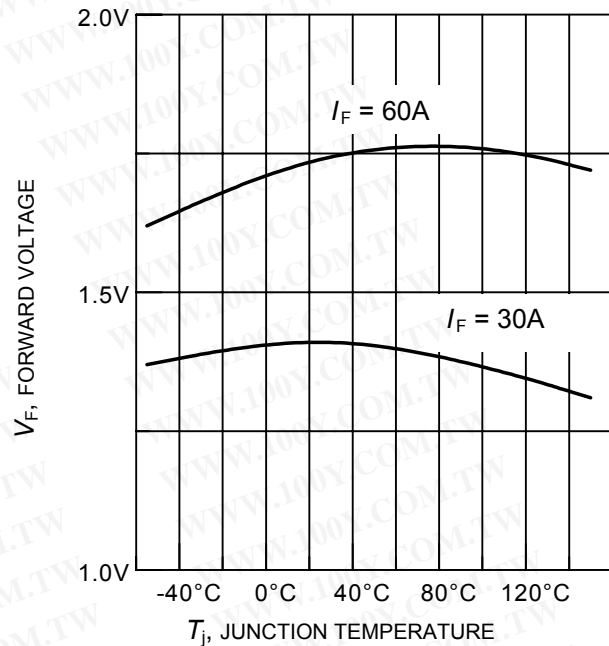
**Figure 23. Typical reverse recovery current as a function of diode current slope**  
 $(V_R = 200V, T_j = 125^\circ C,$   
 Dynamic test circuit in Figure E)



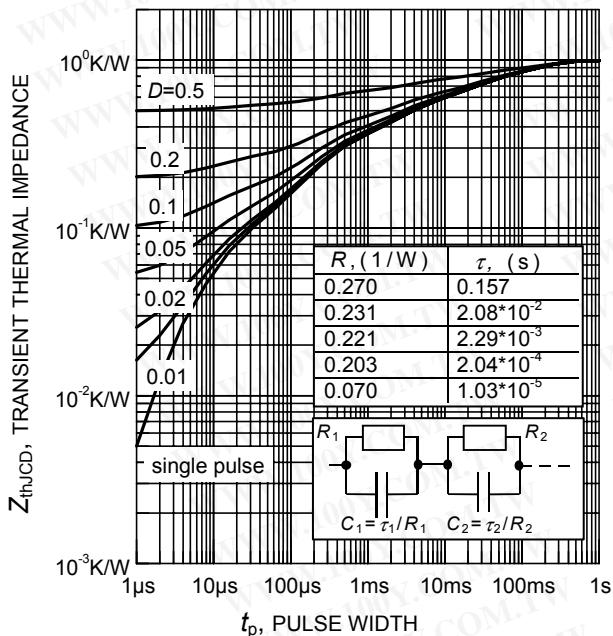
**Figure 24. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**  
 $(V_R = 200V, T_j = 125^\circ C,$   
 Dynamic test circuit in Figure E)



**Figure 25. Typical diode forward current as a function of forward voltage**



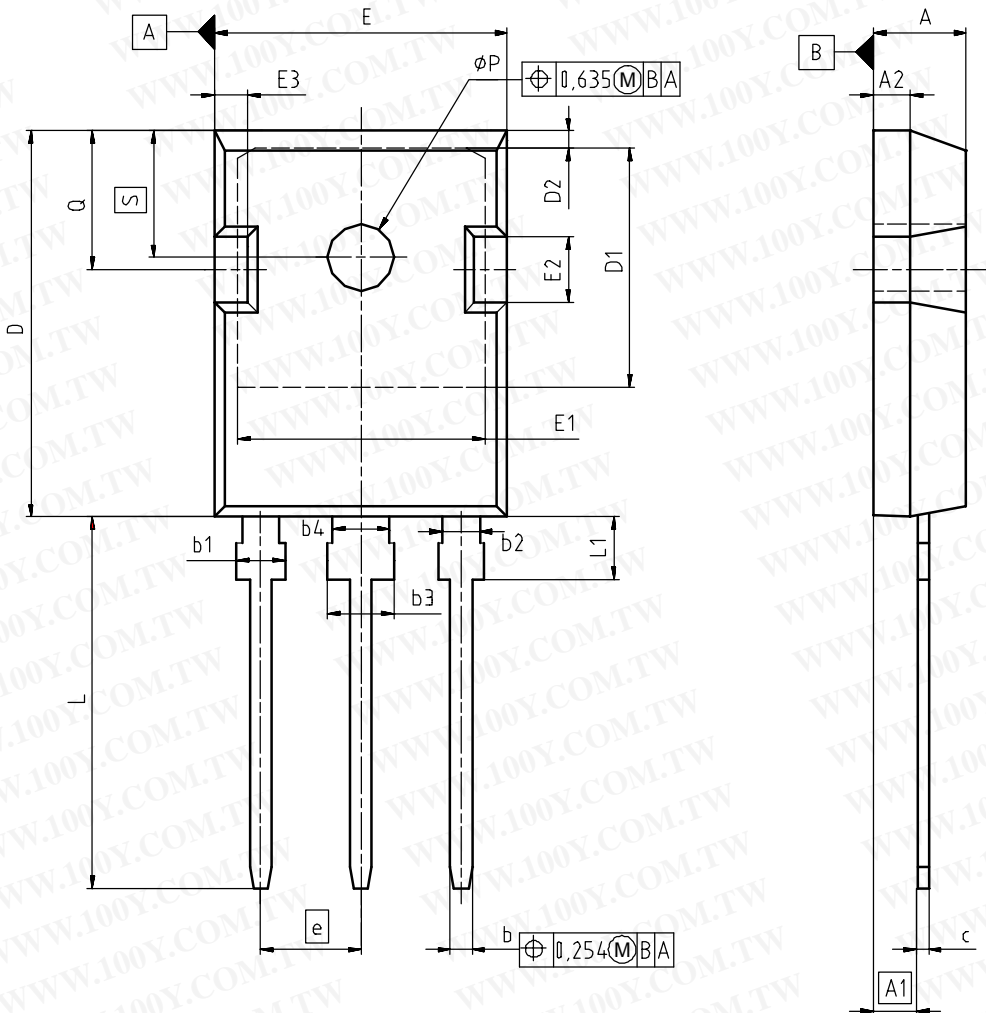
**Figure 26. Typical diode forward voltage as a function of junction temperature**



**Figure 27. Diode transient thermal impedance as a function of pulse width ( $D = t_p / T$ )**

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 勝特力电子(深圳) 86-755-83298787  
[Http://www.100y.com.tw](http://www.100y.com.tw)

## PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.16	0.193	0.203
A1	2.27	2.53	0.089	0.099
A2	1.85	2.11	0.073	0.083
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.82	21.10	0.820	0.831
D1	16.25	17.65	0.640	0.695
D2	1.05	1.35	0.041	0.053
E	15.70	16.03	0.618	0.631
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.68	2.60	0.066	0.102
e	5.44		0.214	
N	3		3	
L	19.80	20.31	0.780	0.799
L1	4.17	4.47	0.164	0.176
$\phi P$	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

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SCALE

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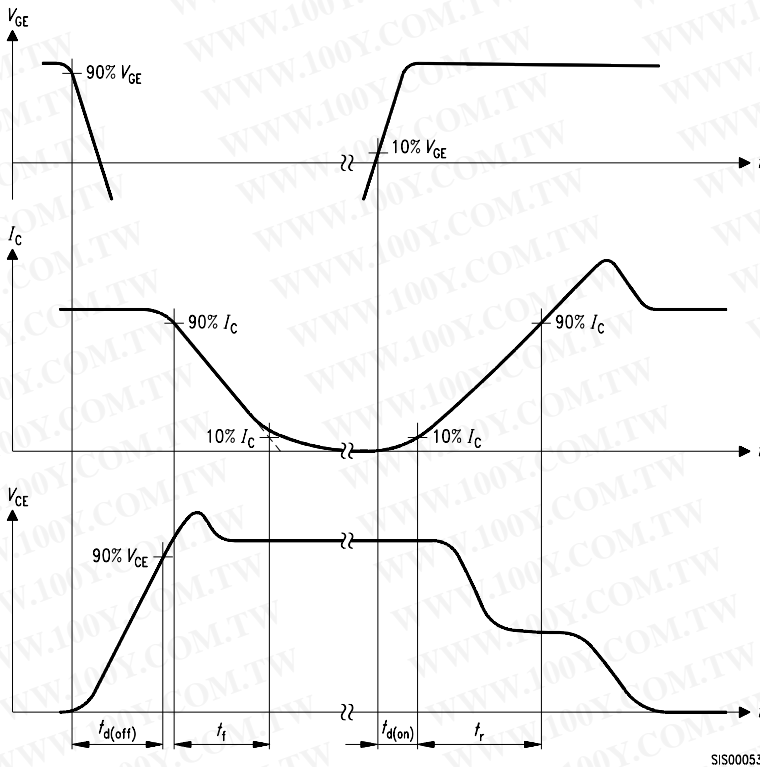


Figure A. Definition of switching times

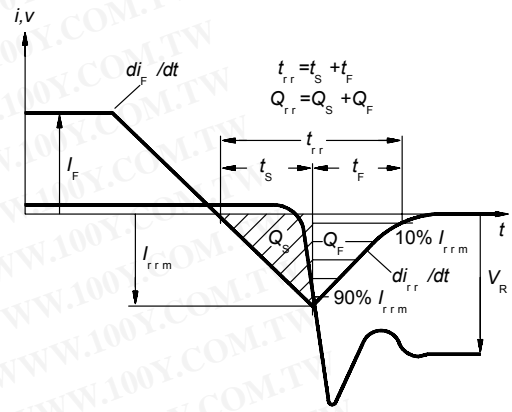


Figure C. Definition of diodes switching characteristics

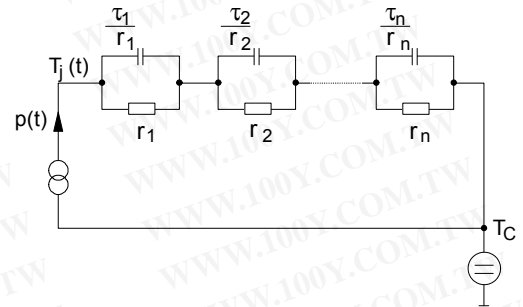


Figure D. Thermal equivalent circuit

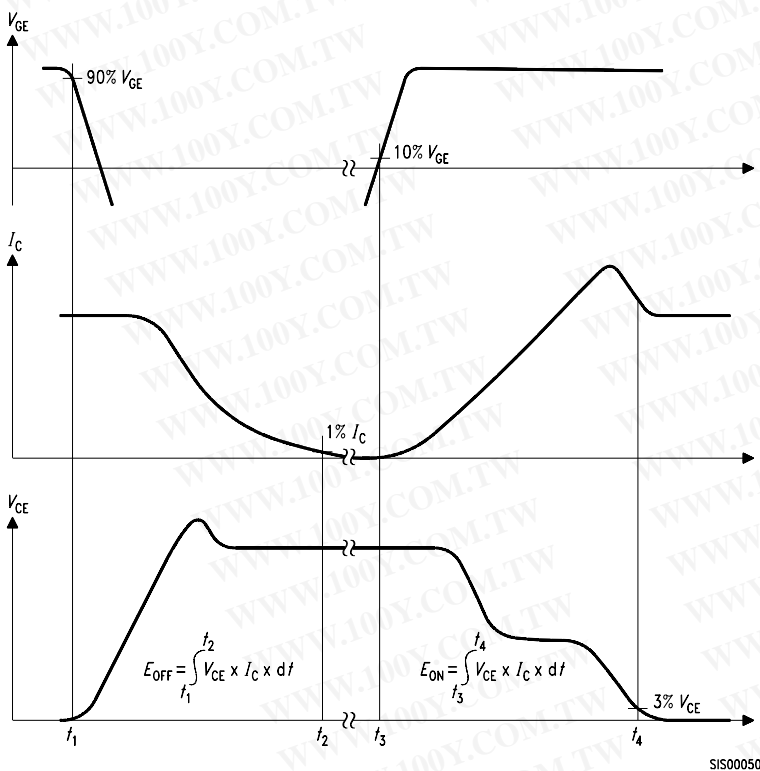


Figure B. Definition of switching losses

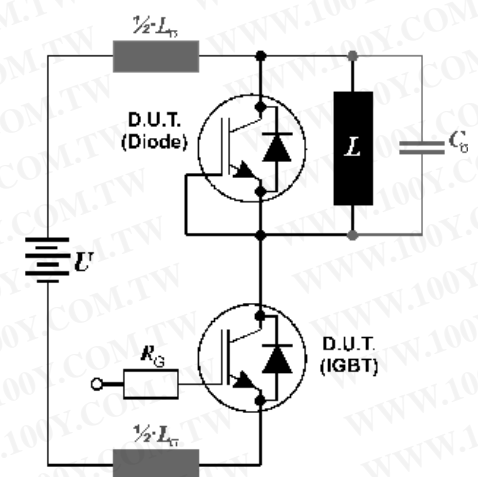


Figure E. Dynamic test circuit  
 Leakage inductance  $L_{\sigma} = 180\text{nH}$   
 and Stray capacity  $C_{\sigma} = 900\text{pF}$ .

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